

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Applicant: Talieh, et al.

Examiner: Not Assigned

Serial No. 09/941,360

Art Unit: 1741

Filed: August 28, 2001

Title: METHOD AND APPARATUS FOR POLISHING A SEMICONDUCTOR  
SUBSTRATE

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3/2  
3/85  
2/7/2  
November 8, 2001

PRELIMINARY AMENDMENT

Hon. Asst. Commissioner for Patents  
Washington, D.C. 20231

Sir/Madam:

Prior to action and/or consideration, kindly enter the following amendments and  
remarks. Please examine the above-identified application in view of the following  
Preliminary Amendment.

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IN THE SPECIFICATION

Page 8, please delete the first full paragraph starting on line 10 and replace with the  
following new paragraph:

Instead of using the cathode contacts 38 described above, the electric potential can be  
applied to the wafer using a ring conductor. Further, other methods of applying the electric  
potential to the wafer may be used in accordance with the present invention. For example, a  
liquid conductor or an inflatable tube coated with a conductive material may be used in the  
present invention. An example of using the liquid conductor or the conductive tube to  
provide the necessary electric potential according to the present invention is disclosed in the